



# **DUAL 20V N-CHANNEL ENHANCEMENT MODE MOSFET**

### **SUMMARY**

 $V_{(BR)DSS}=20V; R_{DS(ON)}=0.025V; I_{D}=6.6A$ 

#### DESCRIPTION

This new generation of high density MOSFETs from Zetex utilises a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.

**SO8** 

#### **FEATURES**

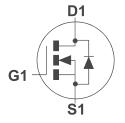
- Low on-resistance
- · Fast switching speed
- · Low threshold
- · Low gate drive
- Low profile SOIC package

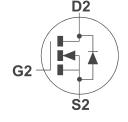
### **APPLICATIONS**

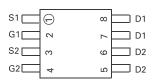
- DC DC Converters
- Power Management Functions
- · Disconnect switches
- Motor control

## ORDERING INFORMATION

DEVICE	REEL SIZE (inches)	TAPE WIDTH (mm)	QUANTITY PER REEL
ZXMD65N02N8TA	13	12mm embossed	1000 units







Top View

#### **DEVICE MARKING**

 ZXMD 65N02

# ZXMD65N02N8

# ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V <sub>DSS</sub>	20	V
Gate- Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current ( $V_{GS}$ =4.5V; $T_A$ =25°C)(b)(d) ( $V_{GS}$ =4.5V; $T_A$ =70°C)(b)(d)	I <sub>D</sub>	6.6 5.3	А
Pulsed Drain Current (c)(d)	I <sub>DM</sub>	26	А
Continuous Source Current (Body Diode)(b)(d)	Is	2.5	А
Pulsed Source Current (Body Diode)(c)(d)	I <sub>SM</sub>	26	А
Power Dissipation at T <sub>A</sub> =25°C (a)(d) Linear Derating Factor	P <sub>D</sub>		W mW/°C
Power Dissipation at T <sub>A</sub> =25°C (a)(e) Linear Derating Factor	P <sub>D</sub>		W mW/°C
Power Dissipation at T <sub>A</sub> =25°C (b)(d) Linear Derating Factor	P <sub>D</sub>	2.0 16	W mW/°C

# THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)(d)	$R_{\theta JA}$	-	°C/W
Junction to Ambient (b)(d)	$R_{\theta JA}$	62.5	°C/W
Junction to Ambient (a)(e)	$R_{\theta JA}$	-	°C/W

### **NOTES**

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions
- (b) For a device surface mounted on FR4 PCB measured at t≤10 secs.
- (c) Repetitive rating pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.
- (d) For device with one active die.
- (e) For device with two active die running at equal power.



# **ZXMD65N02N8**

# **ELECTRICAL CHARACTERISTICS** (at T<sub>amb</sub> = 25°C unless otherwise stated).

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNI T	CONDITIONS.	
STATIC	•		•	•			
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	20			٧	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			1	μΑ	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V	
Gate-Body Leakage	I <sub>GSS</sub>			100	nA	$V_{GS}=\pm 12V, V_{DS}=0V$	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	0.7			V	$I_{D} = 250 \mu A, V_{DS} = V_{GS}$	
Static Drain-Source On-State Resistance (1)	R <sub>DS(on)</sub>			0.025 0.060	Ω	V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A V <sub>GS</sub> =2.5V, I <sub>D</sub> =5A	
Forward Transconductance (3)	g <sub>fs</sub>		20		S	V <sub>DS</sub> =15V,I <sub>D</sub> =6A	
DYNAMIC (3)							
Input Capacitance	C <sub>iss</sub>		-		pF	V 15 V V 0V	
Output Capacitance	C <sub>oss</sub>		-		pF	V <sub>DS</sub> =15 V, V <sub>GS</sub> =0V, f=1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		-		pF		
SWITCHING(2) (3)							
Turn-On Delay Time	t <sub>d(on)</sub>		-		ns	$V_{DD}$ =10V, $I_{D}$ =6A $R_{G}$ =6.0 $\Omega$ , $R_{D}$ =10 $\Omega$ (Refer to test circuit)	
Rise Time	t <sub>r</sub>		-		ns		
Turn-Off Delay Time	t <sub>d(off)</sub>		-		ns		
Fall Time	t <sub>f</sub>		-		ns		
Total Gate Charge	O <sub>g</sub>			-	nC	V <sub>DS</sub> =10V,V <sub>GS</sub> =4.5V I <sub>D</sub> =6A (Refer to test circuit)	
Gate-Source Charge	Q <sub>gs</sub>			-	nC		
Gate Drain Charge	O <sub>gd</sub>			-	nC		
SOURCE-DRAIN DIODE							
Diode Forward Voltage (1)	V <sub>SD</sub>			0.95	V	T <sub>j</sub> =25°C, I <sub>S</sub> =6A, V <sub>GS</sub> =0V	
Reverse Recovery Time (3)	t <sub>rr</sub>		-		ns	T <sub>i</sub> =25°C, I <sub>F</sub> =6A, di/dt= 100A/μs	
Reverse Recovery Charge(3)	Q <sub>rr</sub>		-	1	nC		

<sup>(1)</sup> Measured under pulsed conditions. Width=300 $\mu$ s. Duty cycle  $\leq$ 2% .



<sup>(2)</sup> Switching characteristics are independent of operating junction temperature.

<sup>(3)</sup> For design aid only, not subject to production testing.

# ZXMD65N02N8



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